HN58C256A Series
HN58C257A Series

256k EEPROM (32-kword × 8-bit)
Ready/$\overline{\text{Busy}}$ and $\overline{\text{RES}}$ function (HN58C257A)

REJ03C0148-0600Z
Rev. 6.00
Oct. 26. 2006

Description

Renesas Technology's HN58C256A and HN58C257A are electrically erasable and programmable ROMs organized as 32768-word × 8-bit. They have realized high speed low power consumption and high reliability by employing advanced MNOS memory technology and CMOS process and circuitry technology. They also have a 64-byte page programming function to make their write operations faster.

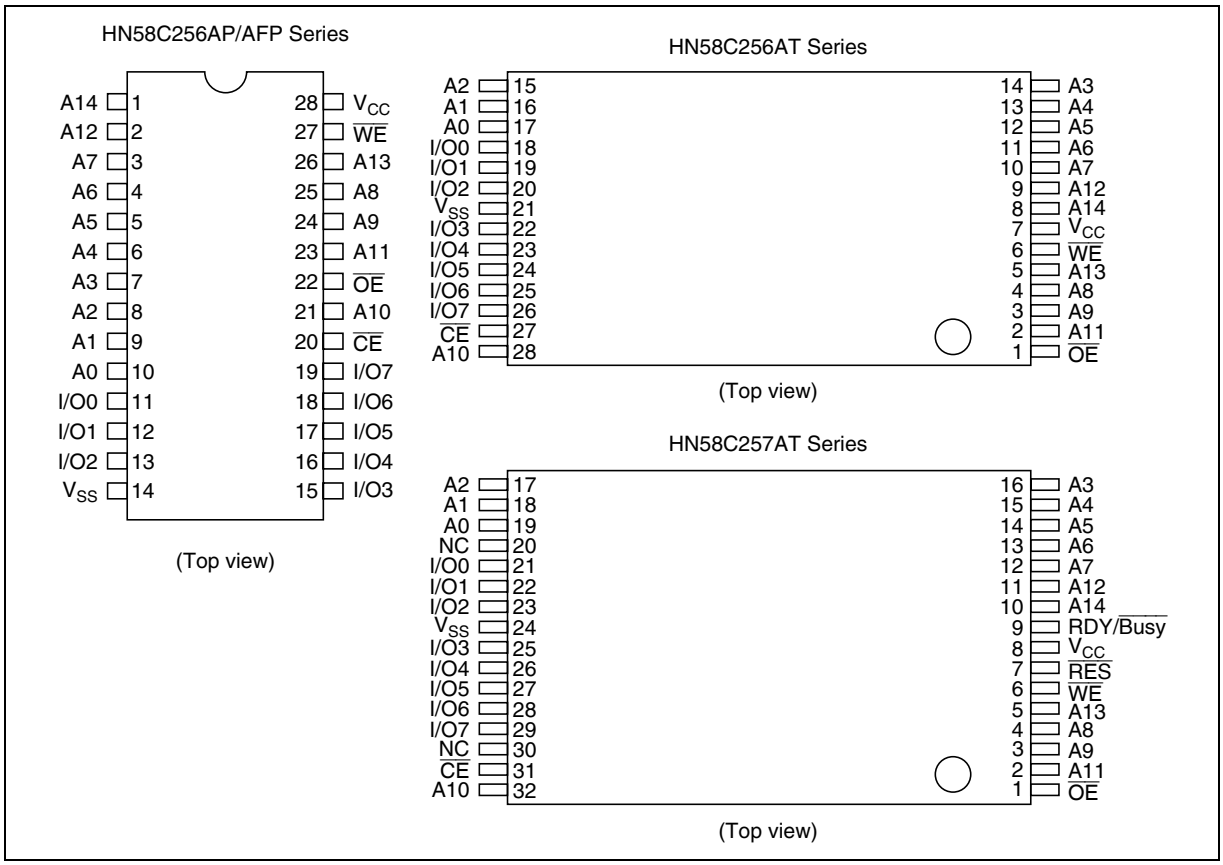
Features

- Single 5 V supply: 5 V ±10%
- Access time: 85 ns/100 ns (max)
- Power dissipation
  - Active: 20 mW/MHz, (typ)
  - Standby: 110 µW (max)
- On-chip latches: address, data, $\overline{\text{CE}}$, $\overline{\text{OE}}$, $\overline{\text{WE}}$
- Automatic byte write: 10 ms max
- Automatic page write (64 bytes): 10 ms max
- Ready/$\overline{\text{Busy}}$ (only the HN58C257A series)
- $\overline{\text{Data}}$ polling and Toggle bit
- Data protection circuit on power on/off
- Conforms to JEDEC byte-wide standard
- Reliable CMOS with MNOS cell technology
- 10^5 erase/write cycles (in page mode)
- 10 years data retention
- Software data protection
- Write protection by $\overline{\text{RES}}$ pin (only the HN58C257A series)
- Industrial versions (Temperatur range: −20 to 85°C and – 40 to 85°C) are also available.
- There are also lead free products.

Ordering Information

Type No.	Access time	Package
HN58C256AP-85 HN58C256AP-10	85 ns 100 ns	600 mil 28-pin plastic DIP PRDP0028AB-A (DP-28)
HN58C256AFP-85 HN58C256AFP-10	85 ns 100 ns	400 mil 28-pin plastic SOP PRSP0028DC-A (FP-28D)
HN58C256AT-85 HN58C256AT-10	85 ns 100 ns	28-pin plastic TSOP PTSA0028ZB-A (TFP-28DB)
HN58C257AT-85 HN58C257AT-10	85 ns 100 ns	32-pin plastic TSOP PTSA0032KD-A (TFP-32DA)
HN58C256AP-85E HN58C256AP-10E	85 ns 100 ns	600 mil 28-pin plastic DIP PRDP0028AB-A (DP-28V) Lead free
HN58C256AFP-85E HN58C256AFP-10E	85 ns 100 ns	400 mil 28-pin plastic SOP PRSP0028DC-A (FP-28DV) Lead free
HN58C256AT-85E HN58C256AT-10E	85 ns 100 ns	28-pin plastic TSOP PTSA0028ZB-A (TFP-28DBV) Lead free
HN58C257AT-85E HN58C257AT-10E	85 ns 100 ns	32-pin plastic TSOP PTSA0032KD-A (TFP-32DAV) Lead free

Pin Arrangement



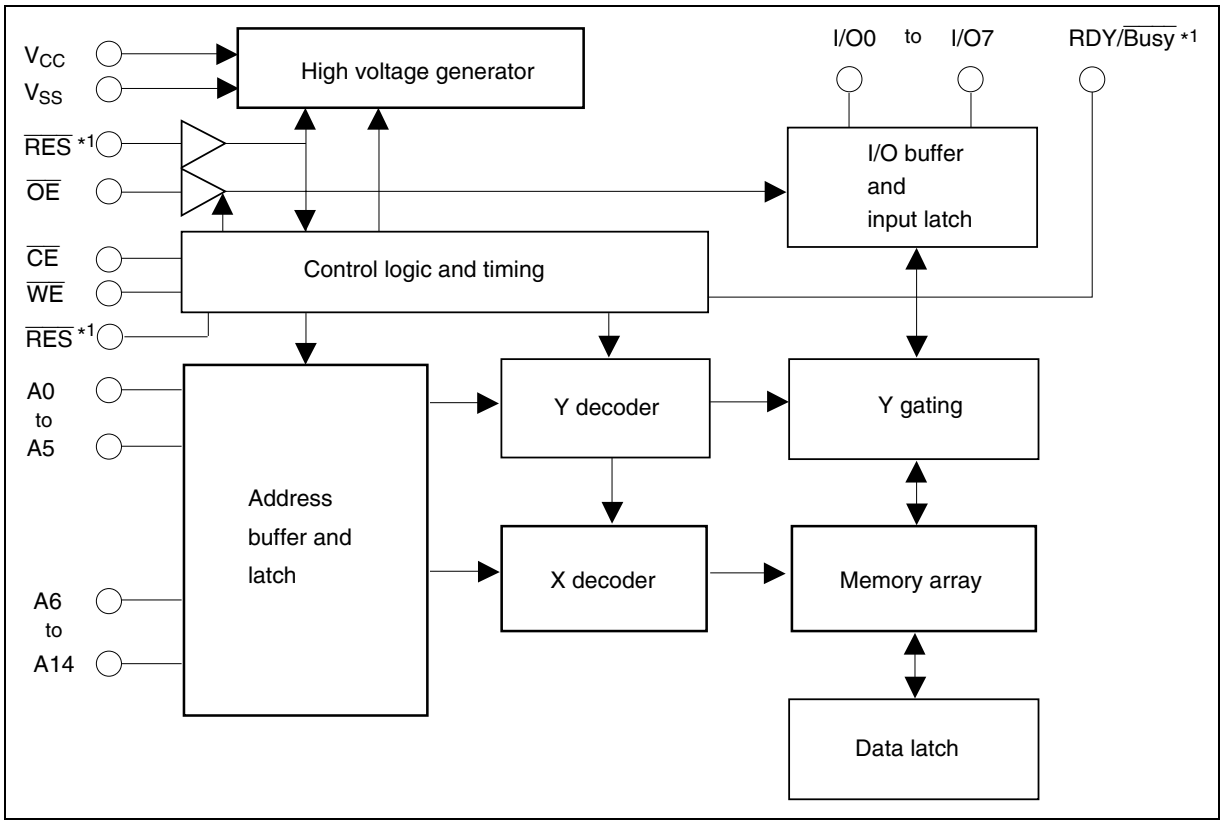
Pin Description

Pin name	Function
A0 to A14	Address input
I/O0 to I/O7	Data input/output
$\overline{OE}$	Output enable
$\overline{CE}$	Chip enable
$\overline{WE}$	Write enable
V_{CC}	Power supply
V_{SS}	Ground
RDY/$\overline{Busy}$*[1]	Ready busy
$\overline{RES}$*[1]	Reset
NC	No connection

Note: 1. This function is supported by only the HN58C257A series.

Block Diagram

Note: 1. This function is supported by only the HN58C257A series.



Operation Table

Operation	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{RES}$*3	RDY/$\overline{Busy}$*3	I/O
Read	V_{IL}	V_{IL}	V_{IH}	V_H*1	High-Z	Dout
Standby	V_{IH}	×*2	×	×	High-Z	High-Z
Write	V_{IL}	V_{IH}	V_{IL}	V_H	High-Z to V_{OL}	Din
Deselect	V_{IL}	V_{IH}	V_{IH}	V_H	High-Z	High-Z
Write inhibit	×	×	V_{IH}	×	—	—
	×	V_{IL}	×	×	—	—
$\overline{Data}$ polling	V_{IL}	V_{IL}	V_{IH}	V_H	V_{OL}	Dout (I/O7)
Program reset	×	×	×	V_{IL}	High-Z	High-Z

Notes: 1. Refer to the recommended DC operating condition.
2. × : Don't care
3. This function is supported by only the HN58C257A series.

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power supply voltage rerative to V_{SS}	V_{CC}	–0.6 to +7.0	V
Input voltage rerative to V_{SS}	Vin	–0.5*1 to +7.0*3	V
Operationg temperature range*2	Topr	0 to +70	°C
Storage temperature range	Tstg	–55 to +125	°C

Notes: 1. Vin min = –3.0 V for pulse width ≤ 50 ns
2. Including electrical characteristics and data retention
3. Should not exceed V_{CC} + 1 V.

Recommended DC Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.5	5.0	5.5	V
	V_{SS}	0	0	0	V
Input voltage	V_{IL}	–0.3*1	—	0.8	V
	V_{IH}	2.2	—	V_{CC} + 0.3*2	V
	V_H*3	V_{CC} –0.5	—	V_{CC} + 1.0	V
Operating temperature	Topr	0	—	+70	°C

Notes: 1. V_{IL} min: –1.0 V for pulse width ≤ 50 ns.
2. V_{IH} max: V_{CC} + 1.0 V for pulse width ≤ 50 ns.
3. This function is supported by only the HN58C257A series.

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5.0 V ±10%)

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Input leakage current	I_{LI}	—	—	2*[1]	µA	V_{CC} = 5.5 V, Vin = 5.5 V
Output leakage current	I_{LO}	—	—	2	µA	V_{CC} = 5.5 V, Vout = 5.5/0.4 V
Standby V_{CC} current	I_{CC1}	—	—	20	µA	$\overline{CE}$ = V_{CC}
	I_{CC2}	—	—	1	mA	$\overline{CE}$ = V_{IH}
Operating V_{CC} current	I_{CC3}	—	—	12	mA	Iout = 0 mA, Duty = 100%, Cycle = 1 µs, V_{CC} = 5.5 V
		—	—	30	mA	Iout = 0 mA, Duty = 100%, Cycle = 85 ns, V_{CC} = 5.5 V
Output low voltage	V_{OL}	—	—	0.4	V	I_{OL} = 2.1 mA
Output high voltage	V_{OH}	2.4	—	—	V	I_{OH} = –400 µA

Note: 1. I_{LI} on $\overline{RES}$ = 100 µA max (only the HN58C257A series)

Capacitance (Ta = +25°C, f = 1 MHz)

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Input capacitance*[1]	Cin	—	—	6	pF	Vin = 0 V
Output capacitance*[1]	Cout	—	—	12	pF	Vout = 0 V

Note: 1. This parameter is periodically sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V±10%)

Test Conditions

- Input pulse levels: 0.4 V to 3.0 V, 0 V to V_{CC} ($\overline{RES}$ pin*[2])
- Input rise and fall time: ≤ 5 ns
- Input timing reference levels: 0.8, 2.0 V
- Output load: 1TTL Gate +100 pF
- Output reference levels: 1.5 V, 1.5 V

Read Cycle

		HN58C256A/HN58C257A					
		-85		-10			
Parameter	Symbol	Min	Max	Min	Max	Unit	Test conditions
Address to output delay	t_{ACC}	—	85	—	100	ns	$\overline{CE}$ = $\overline{OE}$ = V_{IL}, $\overline{WE}$ = V_{IH}
$\overline{CE}$ to output delay	t_{CE}	—	85	—	100	ns	$\overline{OE}$ = V_{IL}, $\overline{WE}$ = V_{IH}
$\overline{OE}$ to output delay	t_{OE}	10	40	10	50	ns	$\overline{CE}$ = V_{IL}, $\overline{WE}$ = V_{IH}
Address to output hold	t_{OH}	0	—	0	—	ns	$\overline{CE}$ = $\overline{OE}$ = V_{IL}, $\overline{WE}$ = V_{IH}
$\overline{OE}$ ($\overline{CE}$) high to output float*[1]	t_{DF}	0	40	0	40	ns	$\overline{CE}$ = V_{IL}, $\overline{WE}$ = V_{IH}
$\overline{RES}$ low to output float*[1, 2]	t_{DFR}	0	350	0	350	ns	$\overline{CE}$ = $\overline{OE}$ = V_{IL}, $\overline{WE}$ = V_{IH}
$\overline{RES}$ to output delay*[2]	t_{RR}	0	450	0	450	ns	$\overline{CE}$ = $\overline{OE}$ = V_{IL}, $\overline{WE}$ = V_{IH}

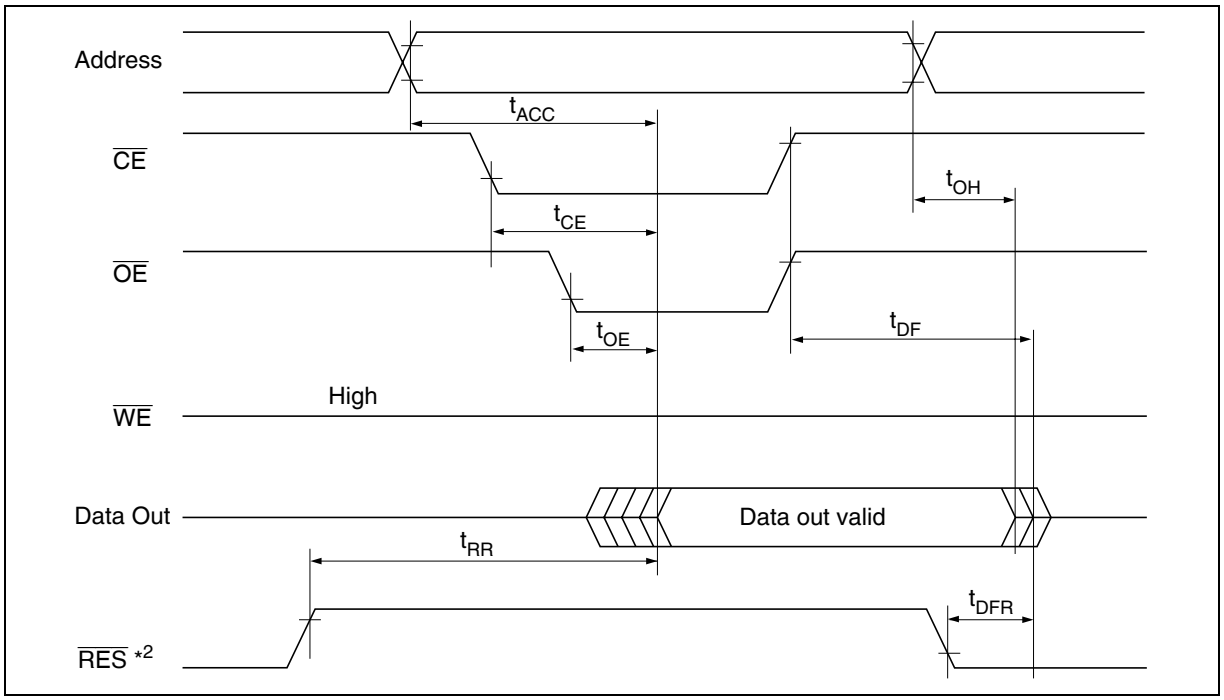
Write Cycle

Parameter	Symbol	Min*[3]	Typ	Max	Unit	Test conditions
Address setup time	t_{AS}	0	—	—	ns	
Address hold time	t_{AH}	50	—	—	ns	
$\overline{CE}$ to write setup time ($\overline{WE}$ controlled)	t_{CS}	0	—	—	ns	
$\overline{CE}$ hold time ($\overline{WE}$ controlled)	t_{CH}	0	—	—	ns	
$\overline{WE}$ to write setup time ($\overline{CE}$ controlled)	t_{WS}	0	—	—	ns	
$\overline{WE}$ hold time ($\overline{CE}$ controlled)	t_{WH}	0	—	—	ns	
$\overline{OE}$ to write setup time	t_{OES}	0	—	—	ns	
$\overline{OE}$ hold time	t_{OEH}	0	—	—	ns	
Data setup time	t_{DS}	50	—	—	ns	
Data hold time	t_{DH}	0	—	—	ns	
$\overline{WE}$ pulse width ($\overline{WE}$ controlled)	t_{WP}	100	—	—	ns	
$\overline{CE}$ pulse width ($\overline{CE}$ controlled)	t_{CW}	100	—	—	ns	
Data latch time	t_{DL}	50	—	—	ns	
Byte load cycle	t_{BLC}	0.2	—	30	µs	
Byte load window	t_{BL}	100	—	—	µs	
Write cycle time	t_{WC}	—	—	10*[4]	ms	
Time to device busy	t_{DB}	120	—	—	ns	
Write start time	t_{DW}	0*[5]	—	—	ns	
Reset protect time*[2]	t_{RP}	100	—	—	µs	
Reset high time*[2, 6]	t_{RES}	1	—	—	µs	

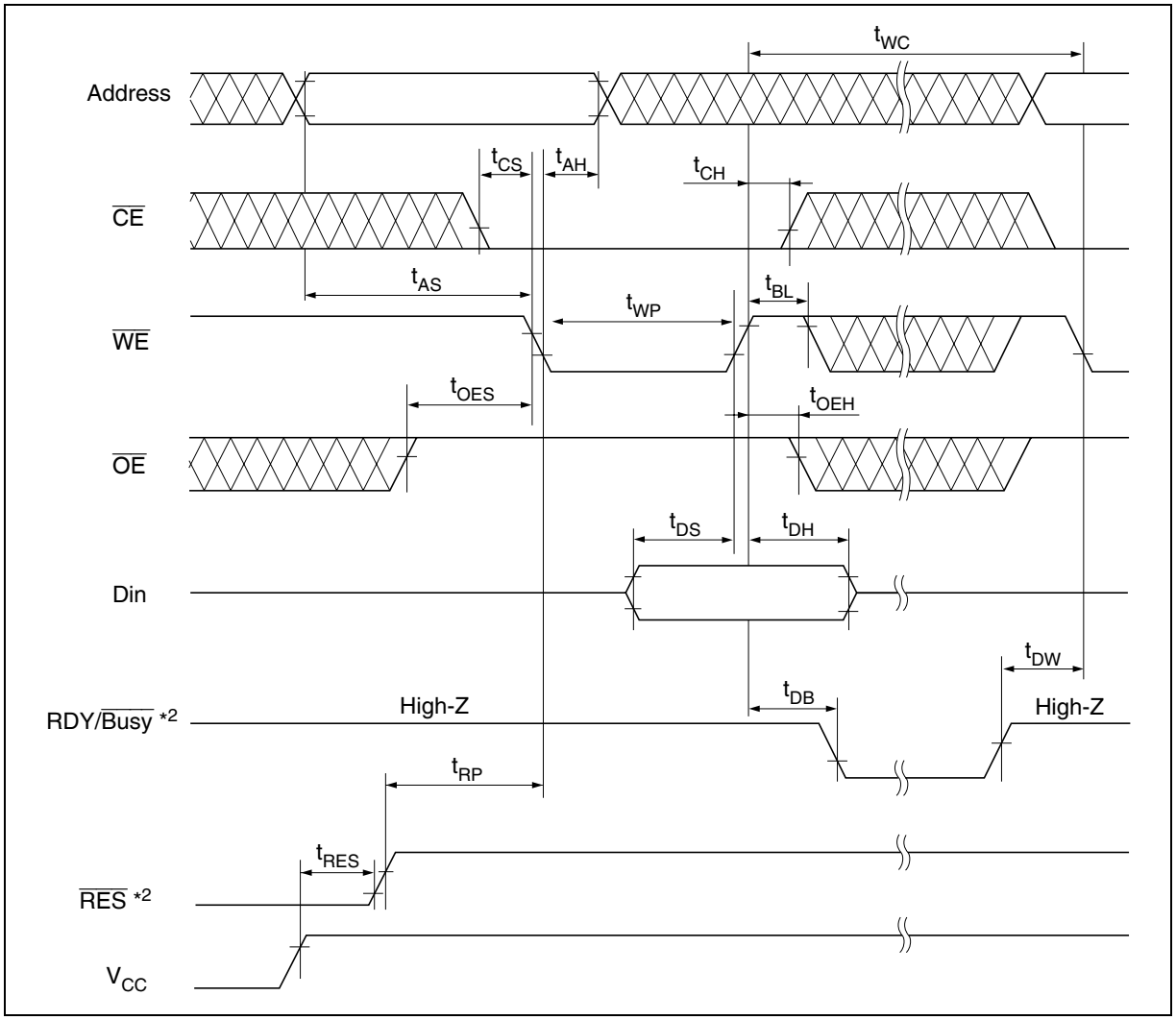
Notes: 1. t_{DF} and t_{DFR} are defined as the time at which the outputs achieve the open circuit conditions and are no longer driven.
2. This function is supported by only the HN58C257A series.
3. Use this device in longer cycle than this value.
4. t_{WC} must be longer than this value unless polling techniques or RDY/$\overline{Busy}$ (only the HN58C257A series) are used. This device automatically completes the internal write operation within this value.
5. Next read or write operation can be initiated after t_{DW} if polling techniques or RDY/$\overline{Busy}$ (only the HN58C257A series) are used.
6. This parameter is sampled and not 100% tested.
7. A6 through A14 are page address and these addresses are latched at the first falling edge of $\overline{WE}$.
8. A6 through A14 are page address and these addresses are latched at the first falling edge of $\overline{CE}$.
9. See AC read characteristics.

Timing Waveforms

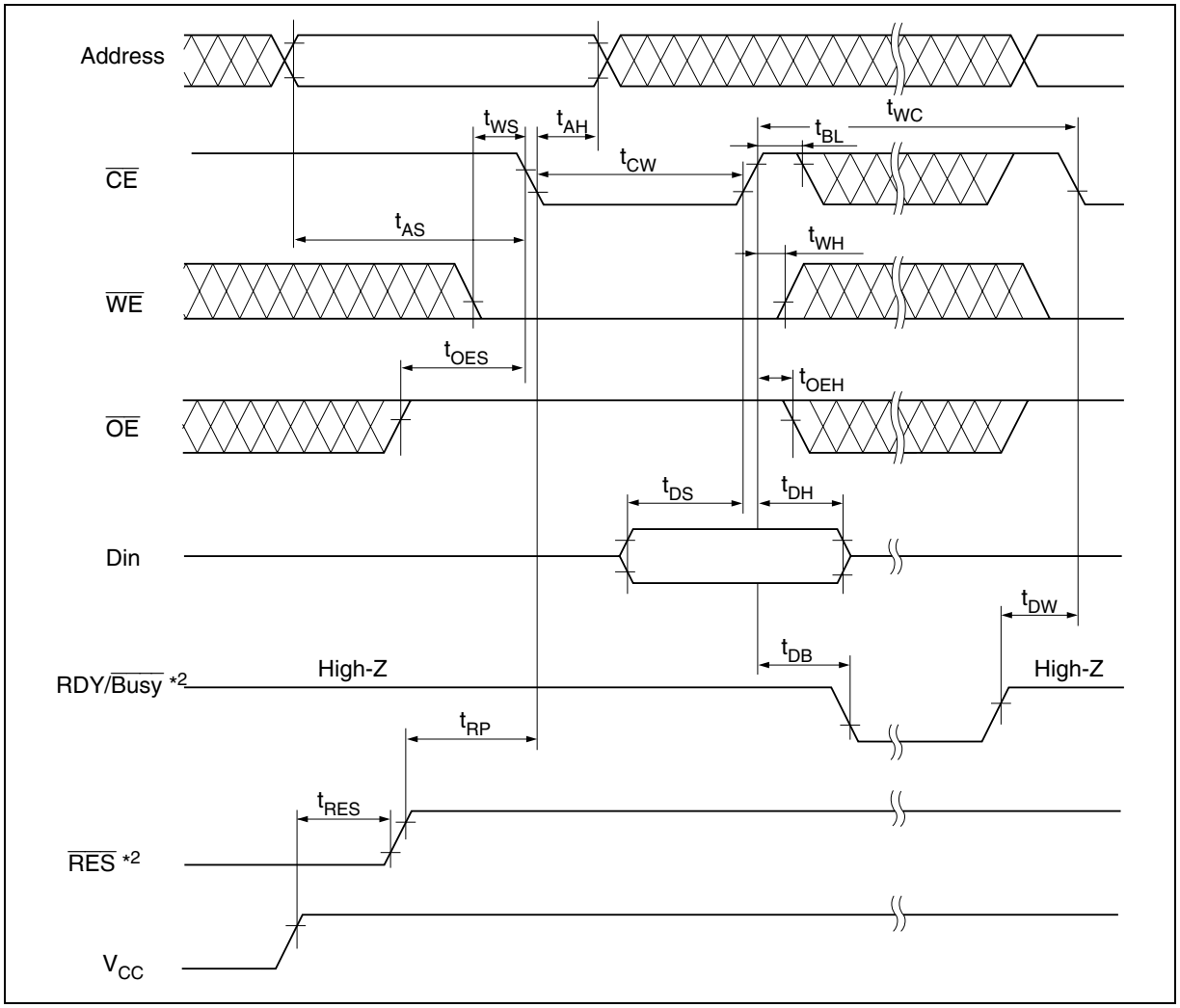
Read Timing Waveform



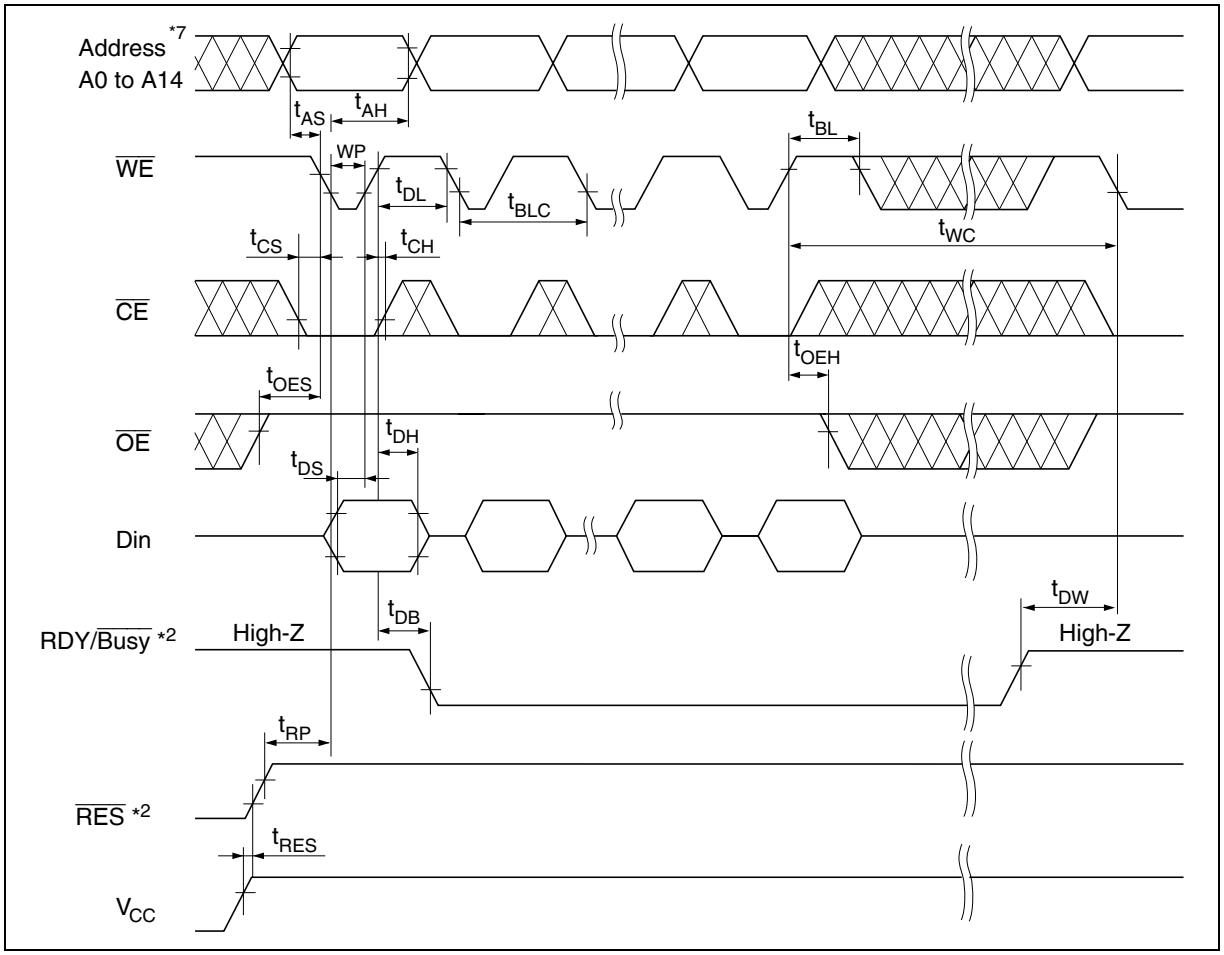
Byte Write Timing Waveform (1) ($\overline{WE}$ Controlled)



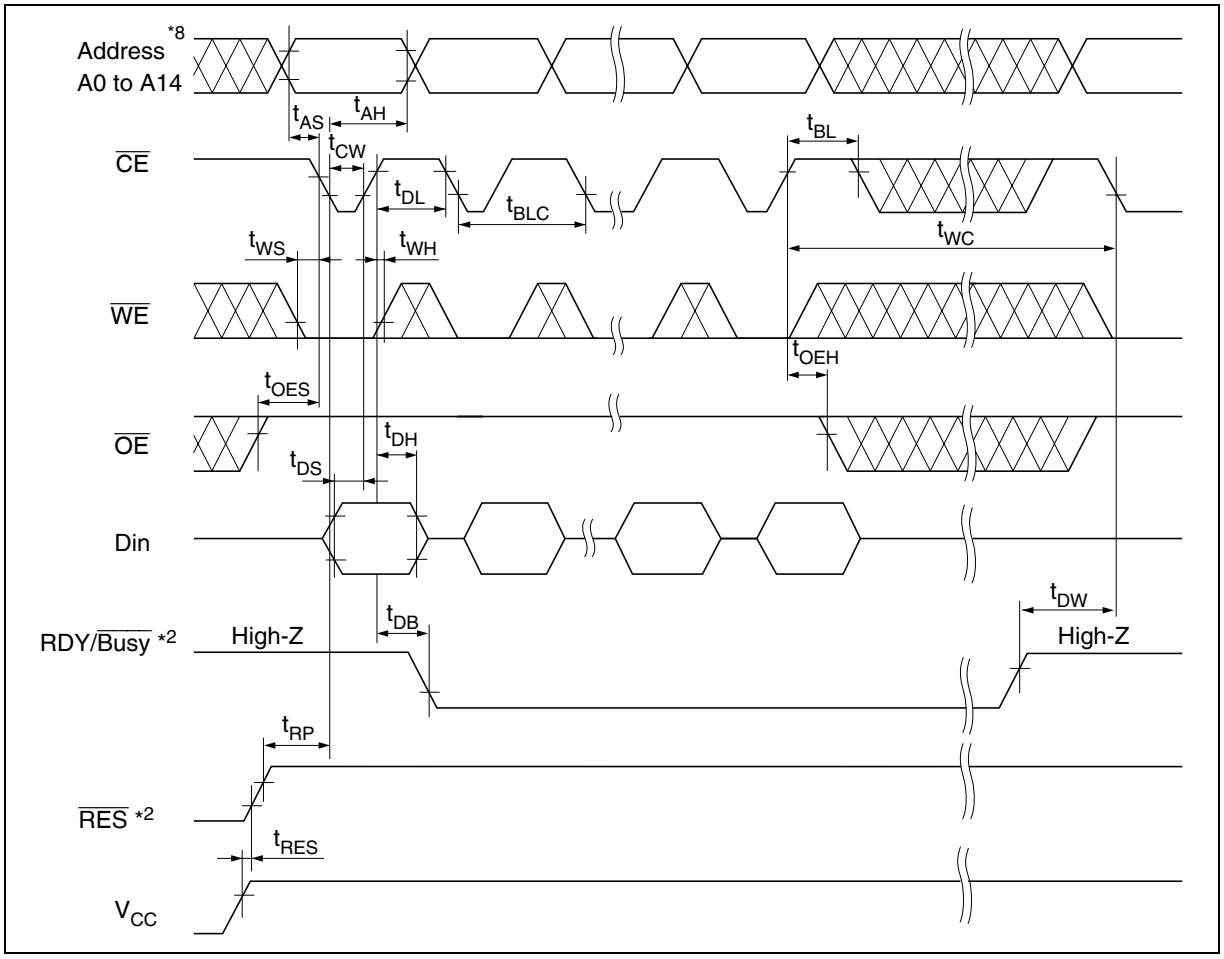
Byte Write Timing Waveform (2) ($\overline{CE}$ Controlled)



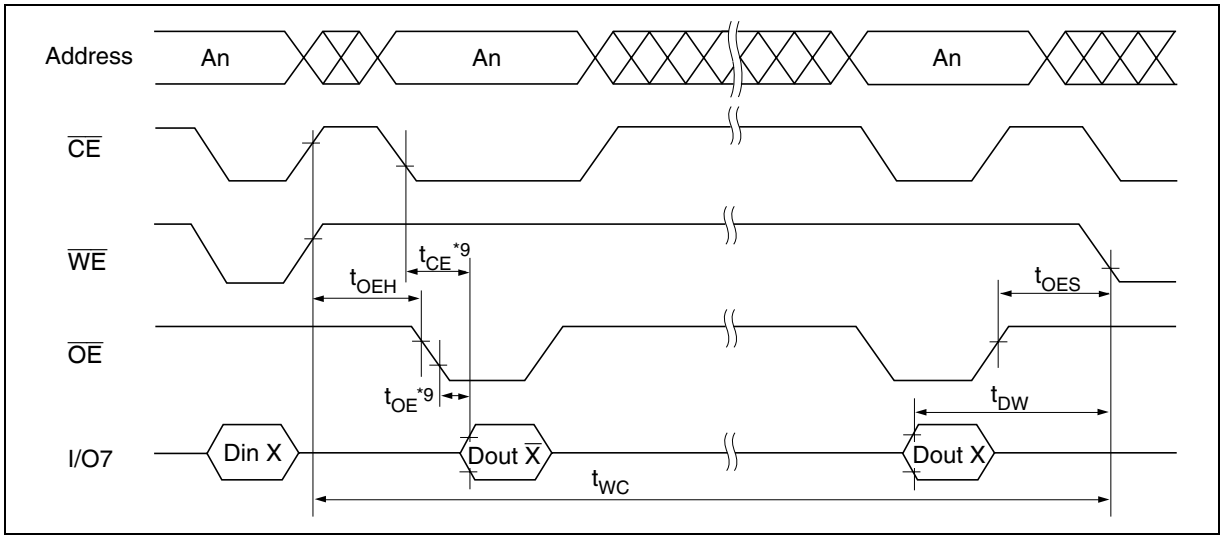
Page Write Timing Waveform (1) ($\overline{WE}$ Controlled)



Page Write Timing Waveform (2) ($\overline{CE}$ Controlled)



$\overline{\text{Data}}$ Polling Timing Waveform

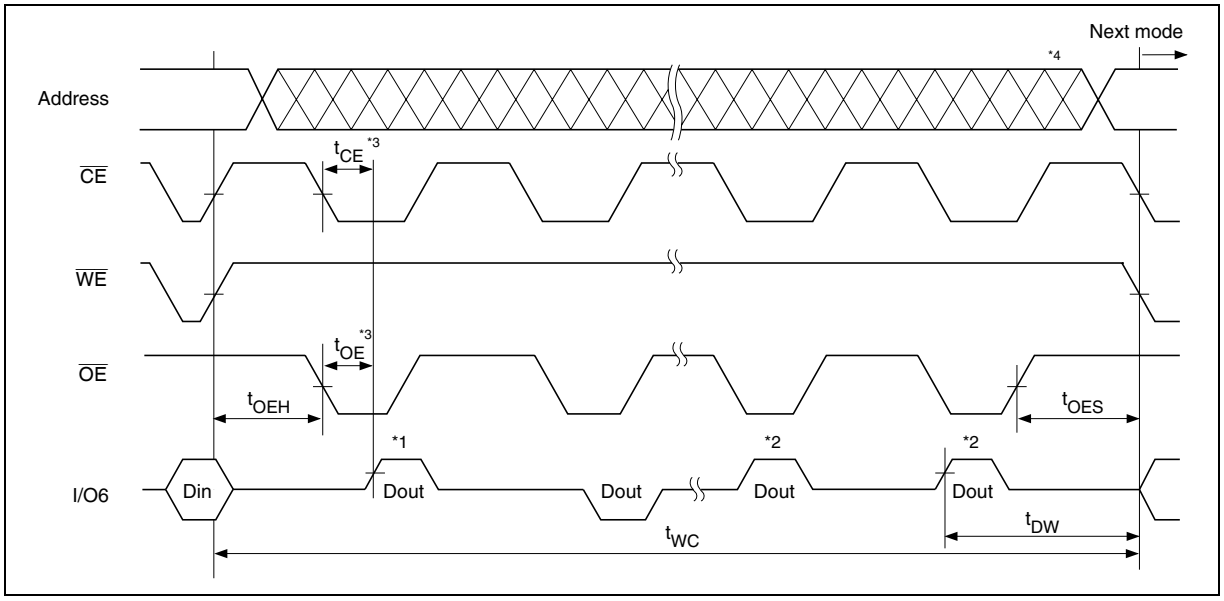


Toggle bit

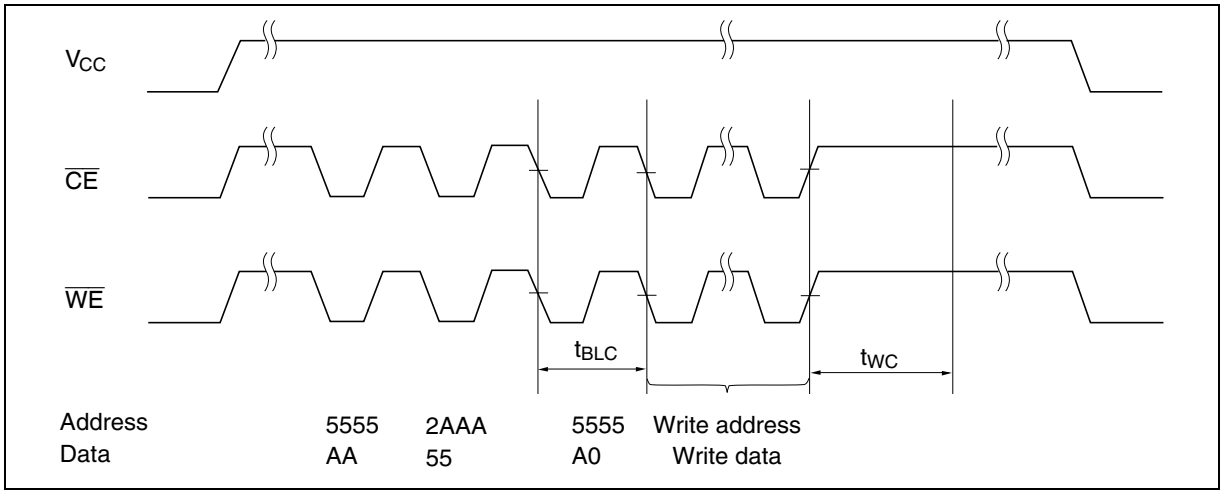
This device provide another function to determine the internal programming cycle. If the EEPROM is set to read mode during the internal programming cycle, I/O6 will charge from “1” to “0” (toggling) for each read. When the internal programming cycle is finished, toggling of I/O6 will stop and the device can be accessible for next read or program.

Toggle bit Waveform

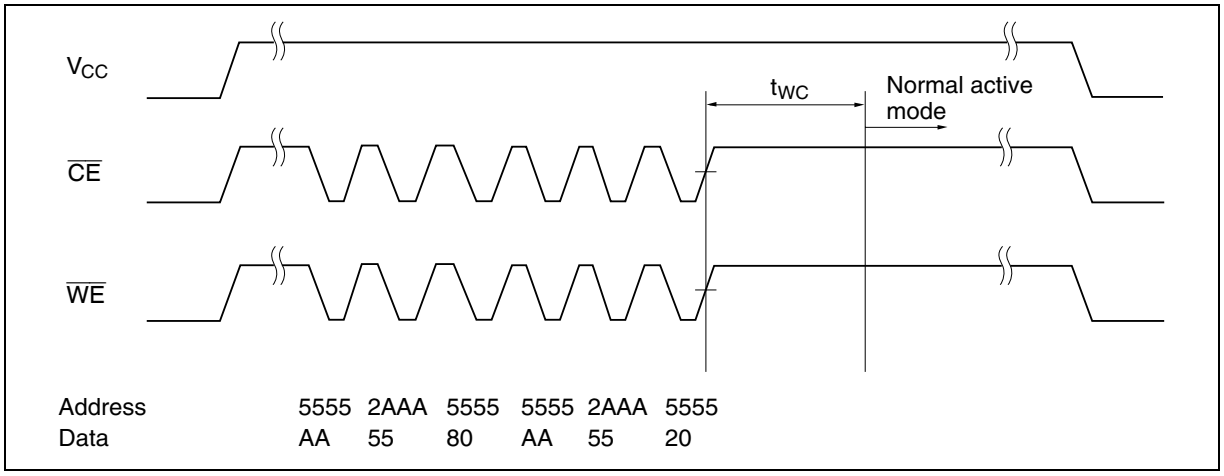
Notes: 1. I/O6 beginning state is "1".
2. I/O6 ending state will vary.
3. See AC read characteristics.
4. Any address location can be used, but the address must be fixed.



Software Data Protection Timing Waveform (1) (in protection mode)



Software Data Protection Timing Waveform (2) (in non-protection mode)



Functional Description

Automatic Page Write

Page-mode write feature allows 1 to 64 bytes of data to be written into the EEPROM in a single write cycle. Following the initial byte cycle, an additional 1 to 63 bytes can be written in the same manner. Each additional byte load cycle must be started within 30 µs from the preceding falling edge of $\overline{WE}$ or $\overline{CE}$. When $\overline{CE}$ or $\overline{WE}$ is high for 100 µs after data input, the EEPROM enters write mode automatically and the input data are written into the EEPROM.

$\overline{Data}$ Polling

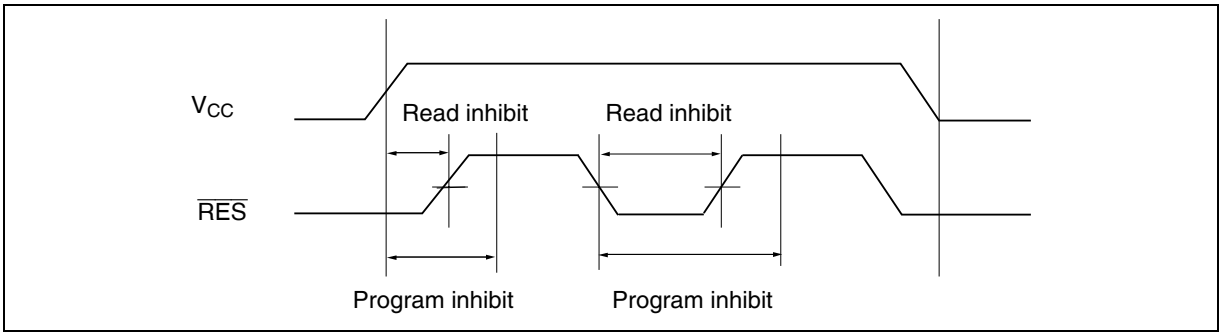
$\overline{Data}$ polling indicates the status that the EEPROM is in a write cycle or not. If EEPROM is set to read mode during a write cycle, an inversion of the last byte of data outputs from I/O7 to indicate that the EEPROM is performing a write operation.

RDY/$\overline{Busy}$ Signal (only the HN58C257A series)

RDY/$\overline{Busy}$ signal also allows status of the EEPROM to be determined. The RDY/$\overline{Busy}$ signal has high impedance except in write cycle and is lowered to V_{OL} after the first write signal. At the end of a write cycle, the RDY/$\overline{Busy}$ signal changes state to high impedance.

$\overline{RES}$ Signal (only the HN58C257A series)

When $\overline{RES}$ is low, the EEPROM cannot be read or programmed. Therefore, data can be protected by keeping $\overline{RES}$ low when V_{CC} is switched. $\overline{RES}$ should be high during read and programming because it doesn't provide a latch function.



$\overline{WE}$, $\overline{CE}$ Pin Operation

During a write cycle, addresses are latched by the falling edge of $\overline{WE}$ or $\overline{CE}$, and data is latched by the rising edge of $\overline{WE}$ or $\overline{CE}$.

Write/Erase Endurance and Data Retention Time

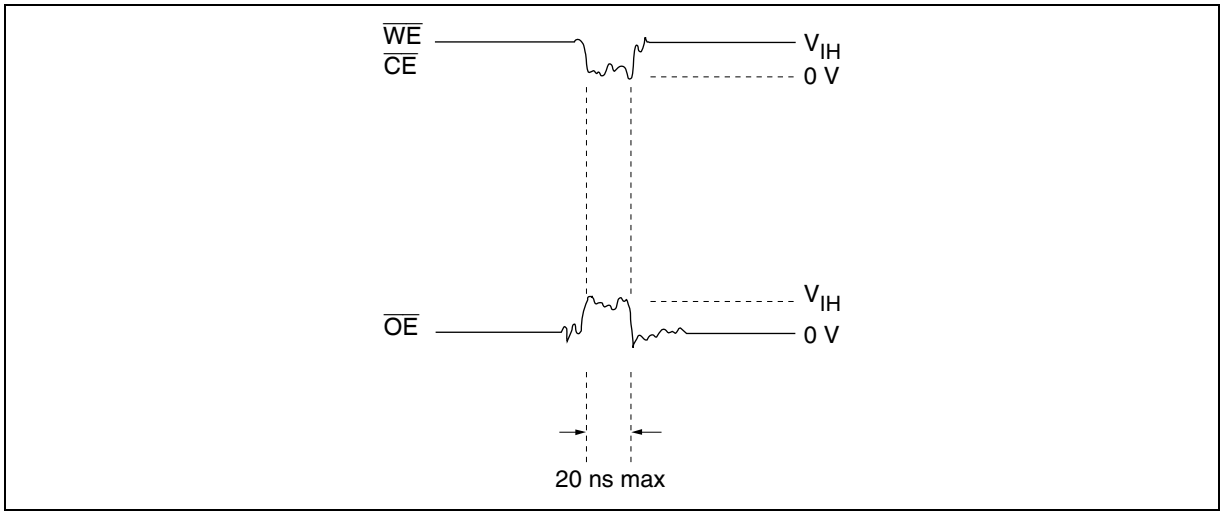
The endurance is 10^5 cycles in case of the page programming and 10^4 cycles in case of the byte programming (1% cumulative failure rate). The data retention time is more than 10 years when a device is page-programmed less than 10^4 cycles.

Data Protection

To prevent this phenomenon, this device has a noise cancelation function that cuts noise if its width is 20 ns or less.

1. Data Protection against Noise on Control Pins ($\overline{CE}$, $\overline{OE}$, $\overline{WE}$) during Operation

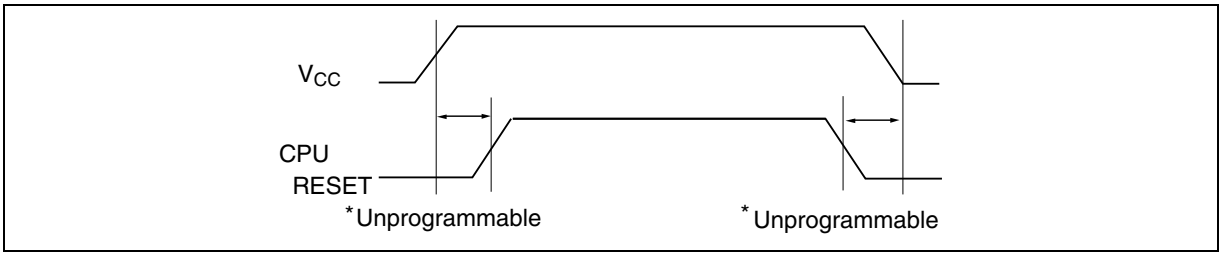
   During readout or standby, noise on the control pins may act as a trigger and turn the EEPROM to programming mode by mistake. Be careful not to allow noise of a width of more than 20 ns on the control pins.



2. Data Protection at V_{CC} On/Off

When V_{CC} is turned on or off, noise on the control pins generated by external circuits (CPU, etc) may act as a trigger and turn the EEPROM to program mode by mistake. To prevent this unintentional programming, the EEPROM must be kept in an unprogrammable state while the CPU is in an unstable state.

Note: The EEPROM shoud be kept in unprogrammable state during V_{CC} on/off by using CPU RESET signal.



2.1 Protection by $\overline{CE}$, $\overline{OE}$, $\overline{WE}$

To realize the unprogrammable state, the input level of control pins must be held as shown in the table below.

$\overline{CE}$	V_{CC}	×	×
$\overline{OE}$	×	V_{SS}	×
$\overline{WE}$	×	×	V_{CC}

×: Don't care.

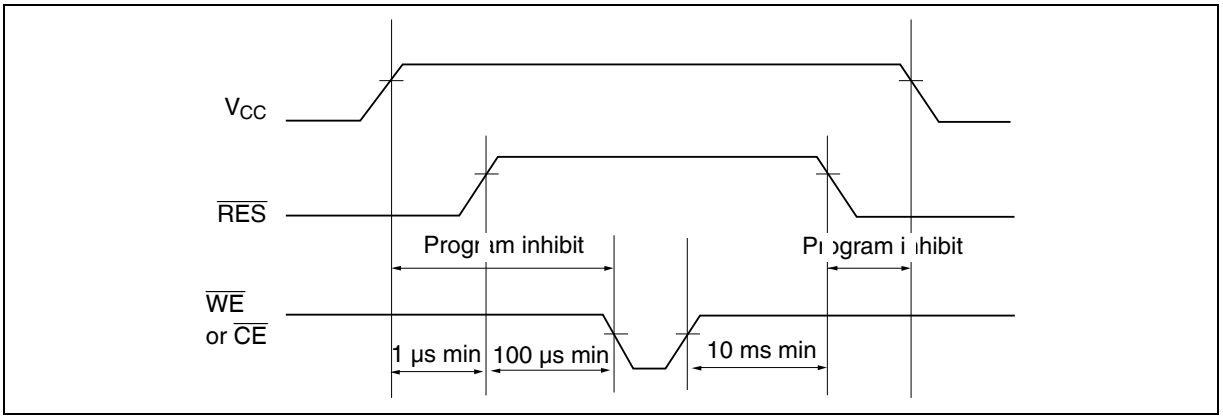
V_{CC}: Pull-up to V_{CC} level.

V_{SS}: Pull-down to V_{SS} level.

2.2 Protection by $\overline{RES}$ (only the HN58C257A series)

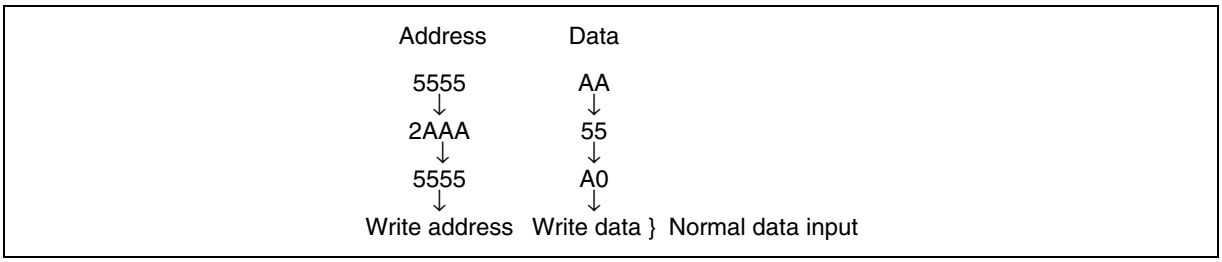
The unprogrammable state can be realized by that the CPU's reset signal inputs directly to the EEPROM's $\overline{RES}$ pin. $\overline{RES}$ should be kept V_{SS} level during V_{CC} on/off.

The EEPROM breaks off programming operation when $\overline{RES}$ becomes low, programming operation doesn't finish correctly in case that $\overline{RES}$ falls low during programming operation. $\overline{RES}$ should be kept high for 10 ms after the last data input.

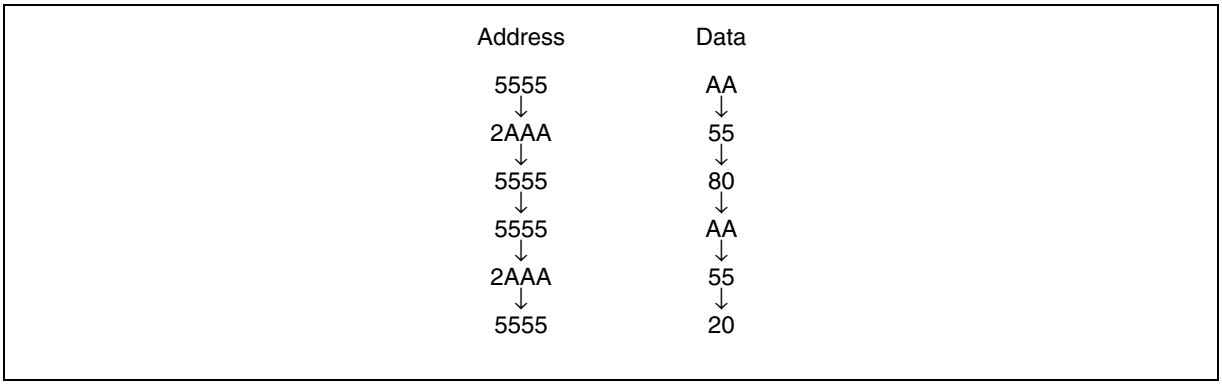


3. Software data protection

To prevent unintentional programming, this device has the software data protection (SDP) mode. The SDP is enabled by inputting the following 3 bytes code and write data. SDP is not enabled if only the 3 bytes code is input. To program data in the SDP enable mode, 3 bytes code must be input before write data.



The SDP mode is disabled by inputting the following 6 bytes code. Note that, if data is input in the SDP disable cycle, data can not be written.



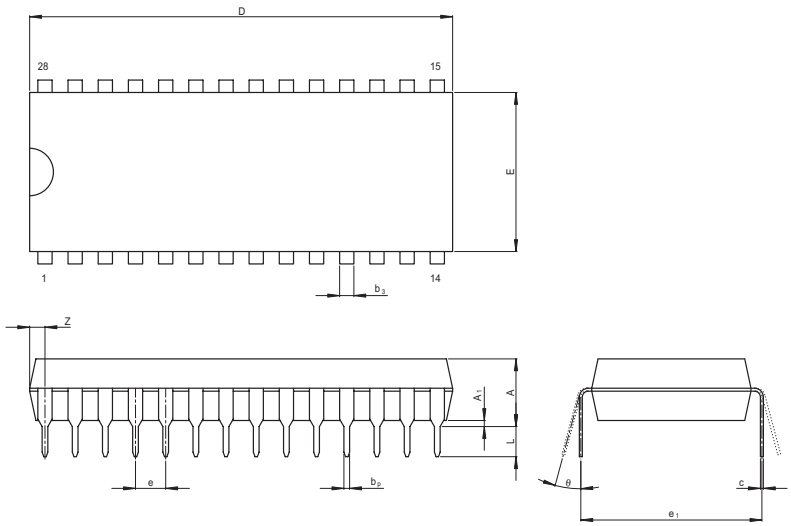
The software data protection is not enabled at the shipment.

Note: There are some differences between Renesas Technology's and other company's for enable/disable sequence of software data protection. If there are any questions , please contact with Renesas Technology's sales offices.

Package Dimensions

HN58C256AP Series (PRDP0028AB-A / Previous Code: DP-28, DP-28V)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP28-13.4x35.6-2.54	PRDP0028AB-A	DP-28/DP-28V	4.6g

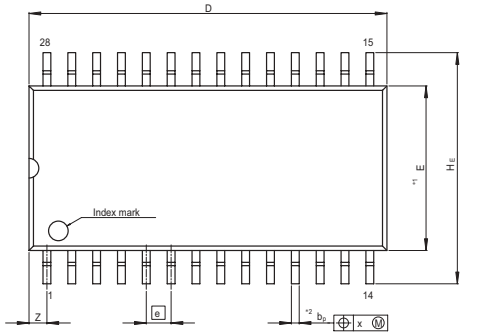


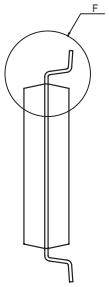
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	—	15.24	—
D	—	35.6	36.5
E	—	13.4	14.6
A	—	—	5.70
A_1	0.51	—	—
b_p	0.38	0.48	0.58
b_3	—	1.2	—
c	0.20	0.25	0.36
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	1.9
L	2.54	—	—

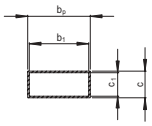
Package Dimensions (cont.)

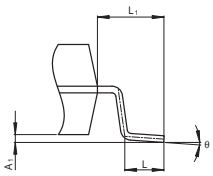
HN58C256AFP Series (PRSP0028DC-A / Previous Code: FP-28D, FP-28DV)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP28-8.4x18.3-1.27	PRSP0028DC-A	FP-28D	0.7g









NOTE)
1. DIMENSION"*1"
   DOES NOT INCLUDE MOLD FLASH.
2. DIMENSION"*2"DOES NOT
   INCLUDE TRIM OFFSET.

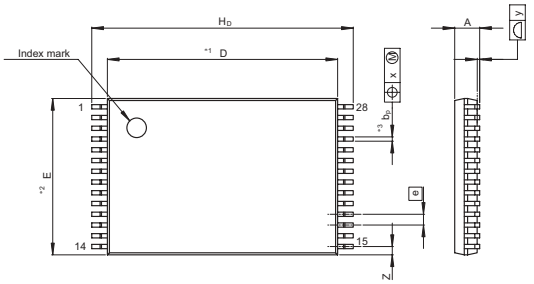
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	18.3	18.8
E	—	8.4	—
A_2	—	—	—
A_1	0.10	0.20	0.30
A	—	—	2.50
b_p	0.32	0.40	0.48
b_1	—	0.38	—
c	0.12	0.17	0.22
c_1	—	0.15	—
θ	0°	—	8°
H_E	11.5	11.8	12.1
e	—	1.27	—
x	—	—	0.20
y	—	—	0.15
Z	—	—	1.12
L	0.8	1.0	1.2
L_1	—	1.7	—

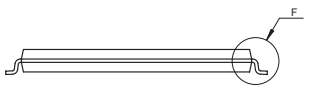
Package Dimensions (cont.)

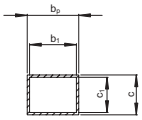
HN58C256AT Series (PTSA0028ZB-A / Previous Code: TFP-28DB, TFP-28DBV)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TSOP(1)28-8x11.8-0.55	PTSA0028ZB-A	TFP-28DB/TFP-28DBV	0.23g

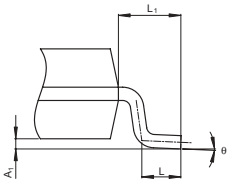
NOTE)
1. DIMENSION"*1"AND"*2(Nom)" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION"*3"DOES NOT INCLUDE TRIM OFFSET.







Terminal cross section



Detail F

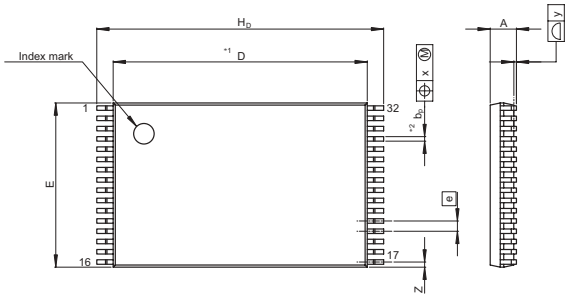
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	11.80	—
E	—	8.00	8.20
A_2	—	—	—
A_1	0.05	0.13	0.20
A	—	—	1.20
b_p	0.14	0.22	0.30
b_1	—	0.20	—
c	0.12	0.17	0.22
c_1	—	0.15	—
θ	0°	—	5°
H_D	13.10	13.40	13.70
e	—	0.55	—
x	—	—	0.10
y	—	—	0.10
Z	—	—	0.45
L	0.40	0.50	0.60
L_1	—	0.80	—

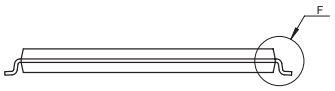
Package Dimensions (cont.)

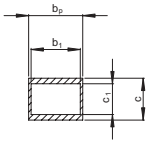
HN58C257AT Series (PTSA0032KD-A / Previous Code: TFP-32DA, TFP-32DAV)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TSOP(1)32-8x12.4-0.50	PTSA0032KD-A	TFP-32DA/TFP-32DAV	0.26g

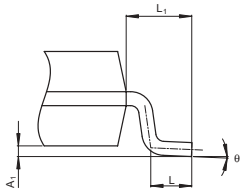
NOTE)
1. DIMENSION"*1"DOES NOT INCLUDE MOLD FLASH.
2. DIMENSION"*2"DOES NOT INCLUDE TRIM OFFSET.







Terminal cross section



Detail F

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.40	—
E	—	8.00	8.20
A_2	—	—	—
A_1	0.08	0.13	0.18
A	—	—	1.20
b_p	0.14	0.22	0.30
b_1	—	0.20	—
c	0.12	0.17	0.22
c_1	—	0.125	—
θ	0°	—	5°
H_D	13.80	14.00	14.20
e	—	0.50	—
x	—	—	0.08
y	—	—	0.10
Z	—	—	0.45
L	0.40	0.50	0.60
L_1	—	0.80	—

Rev.	Date	Contents of Modification	
		Page	**Description**
0.0	Jun. 19. 1995	—	Initial issue
1.0	May. 17. 1996	—	Change of format
		4	Absolute Maximun Ratings Addition of note 4
		4	Recommended DC Operating Conditions V_{IH} (min): 3.0 V to 2.2 V
		5	DC Characteristics V_{OH} (min): $V_{CC} \times 0.8$ V to 2.4 V
		6	AC Characteristics Input pulse levels: 0 V to 3.0 V to 0.4 V to 3.0 V $\overline{\text{Data}}$ Polling Timing Waveform Addition of note 1 Toggle bit Waveform Addition of note 4
2.0	Feb. 27. 1997	4	Recommended DC Operating Conditions V_{IL} (max): 0.6 V to 0.8 V
		16	Functional Description Data Protection 3: Addition of note
3.0	May. 20. 1997	16	Functional Description Data Protection 3: Change of Description
4.0	Oct. 24. 1997	8	Timing Waveforms Read Timing Waveform: Correct error
5.00	Nov. 17. 2003	—	Change format issued by Renesas Technology Corp.
		2	Ordering Information Addition of HN58C256AFP-85E, HN58C256AFP-10E, HN58C256AT-85E, HN58C256AT-10E, HN58C257AT-85E, HN58C257AT-10E
		20-23	Package Dimensions FP-28D to FP-28D, FP-28DV TFP-28DB to TFP-28DB, TFP-28DBV TFP-32DA to TFP-32DA, TFP-32DAV
6.00	Oct. 26, 2006	2	Ordering Information Addition of HN58C256AP-85E, HN58C256AP-10E

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